

Product Change Notification - JAON-03TOQC783

Date: 23 Oct 2017

Product Category: 16-Bit - Microcontrollers and Digital Signal Controllers; Ethernet Controllers; Wireless Modules; 8-bit PIC Microcontrollers

Notification subject: CCB 3002 Final Notice: Qualification of MMT as an additional assembly site using CuPdAu bond wire in selected products of the 0.25um TSMC wafer technology available in 28L SSOP package.

Notification text: **PCN Status:**
Final notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of MMT as an additional assembly site using palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 0.25um TSMC wafer technology available in 28L SSOP package.

Pre Change:

Assembled at MTAI using palladium coated copper (PdCu) bond wire.

Post Change:

Assembled at MTAI using palladium coated copper (PdCu) bond wire or assembled at MMT using palladium coated copper with gold flash (CuPdAu) bond wire.

Pre and Post Change Summary:

	Pre Change	Post Change	
Assembly Site	Microchip Technology Thailand - HQ (MTAI)	Microchip Technology Thailand - HQ (MTAI)	Microchip Technology Thailand - Branch (MMT)
Wire material	PdCu Wire	PdCu Wire	CuPdAu Wire
Die attach material	3280	3280	3280
Molding compound material	G600	G600	G600
Lead frame material	CDA194	CDA194	CDA194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by qualifying MMT as an additional assembly site using palladium coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status:

In Progress

Estimated First Ship Date:

November 24, 2017 (date code: 1747)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	July 2017				-->	October 2017				November 2017			
	27	28	29	30		40	41	42	43	44	45	46	47
Initial PCN Issue Date	X												
Qual Report Availability								X					
Final PCN Issue Date								X					
Estimated Implementation Date													X

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:

July 6, 2017: Issued initial notification.

October 23, 2017: Issued final notification. Provided estimated first ship date to be on November 24, 2017.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

- [PCN_JAON-03TOQC783_Qual_Report.pdf](#)
- [PCN_JAON-03TOQC783_Affected_CPN.pdf](#)
- [PCN_JAON-03TOQC783_Affected_CPN.xls](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PCN_JAON-03TOQC783
CATALOG_PART_NBR
DSPIC33FJ12GP202-E/SS
DSPIC33FJ12GP202-I/SS
DSPIC33FJ12GP202T-E/SS
DSPIC33FJ12GP202T-I/SS
DSPIC33FJ12MC202-E/SS
DSPIC33FJ12MC202-I/SS
DSPIC33FJ12MC202T-E/SS
DSPIC33FJ12MC202T-I/SS
DSPIC33FJ16GP102-I/SS
DSPIC33FJ16MC102-E/SS
DSPIC33FJ16MC102-I/SS
DSPIC33FJ16MC102T-I/SS
DSPIC33FJ32GP102-I/SS
DSPIC33FJ32GP202-E/SS
DSPIC33FJ32GP202-I/SS
DSPIC33FJ32GP202T-E/SS
DSPIC33FJ32GP202T-I/SS
DSPIC33FJ32MC102-I/SS
DSPIC33FJ32MC202-E/SS
DSPIC33FJ32MC202-E/SSC25
DSPIC33FJ32MC202-I/SS
DSPIC33FJ32MC202-I/SSC24
DSPIC33FJ32MC202T-E/SS
DSPIC33FJ32MC202T-I/SS
ENC28J60/SS
ENC28J60-I/SS
ENC28J60T/SS
ENC28J60T-I/SS
MCW1001A-I/SS
MCWA01-I/SS800
MCWA01T-I/SS800
PIC18F24J10-I/SS
PIC18F24J10T-I/SS
PIC18F24J11-I/SS
PIC18F24J11T-I/SS
PIC18F24J50-I/SS
PIC18F24J50T-I/SS
PIC18F25J10-I/SS
PIC18F25J10T-I/SS
PIC18F25J11-I/SS
PIC18F25J11T-I/SS
PIC18F25J50-I/SS
PIC18F25J50-I/SS022
PIC18F25J50-I/SS024
PIC18F25J50-I/SS027

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Affected Catalog Part Numbers (CPN)

PCN_JAON-03TOQC783
CATALOG_PART_NBR
PIC18F25J50-I/SS028
PIC18F25J50-I/SS029
PIC18F25J50-I/SS030
PIC18F25J50T-I/SS
PIC18F26J11-I/SS
PIC18F26J11T-I/SS
PIC18F26J13-I/SS
PIC18F26J13T-I/SS
PIC18F26J50-I/SS
PIC18F26J50-I/SS020
PIC18F26J50T-I/SS
PIC18F26J50T-I/SS020
PIC18F26J50T-I/SS033
PIC18F26J50T-I/SS034
PIC18F26J53-I/SS
PIC18F26J53T-I/SS
PIC18F27J13-I/SS
PIC18F27J13T-I/SS
PIC18F27J53-I/SS
PIC18F27J53T-I/SS
PIC18LF24J10-I/SS
PIC18LF24J11-I/SS
PIC18LF24J11T-I/SS
PIC18LF24J50-I/SS
PIC18LF24J50T-I/SS
PIC18LF25J10-I/SS
PIC18LF25J10T-I/SS
PIC18LF25J10T-I/SS032
PIC18LF25J10T-I/SS033
PIC18LF25J10T-I/SS035
PIC18LF25J10T-I/SS038
PIC18LF25J10T-I/SS039
PIC18LF25J10T-I/SS040
PIC18LF25J10T-I/SS041
PIC18LF25J10T-I/SS042
PIC18LF25J11-I/SS
PIC18LF25J11T-I/SS
PIC18LF25J50-I/SS
PIC18LF25J50T-I/SS
PIC18LF26J11-I/SS
PIC18LF26J11T-I/SS
PIC18LF26J13-I/SS
PIC18LF26J13T-I/SS
PIC18LF26J50-I/SS
PIC18LF26J50T-I/SS

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Affected Catalog Part Numbers (CPN)

PCN_JAON-03TOQC783
CATALOG_PART_NBR
PIC18LF26J53-I/SS
PIC18LF26J53T-I/SS
PIC18LF27J13-I/SS
PIC18LF27J13T-I/SS
PIC18LF27J53-I/SS
PIC18LF27J53T-I/SS
PIC24FJ16MC102-E/SS
PIC24FJ16MC102-I/SS
PIC24FJ16MC102T-I/SS
PIC24FJ32MC102-I/SS
PIC24HJ12GP202-E/SS
PIC24HJ12GP202-I/SS
PIC24HJ12GP202T-E/SS
PIC24HJ12GP202T-I/SS
PIC24HJ32GP202-E/SS
PIC24HJ32GP202-I/SS
PIC24HJ32GP202T-E/SS
PIC24HJ32GP202T-I/SS